REMARKS

Claims 100-112 are pending in the present application. In the Office Action dated July 14, 2005, claims 89-94 were rejected under 35 U.S.C. 103(a) as being unpatentable over Crevasse et al. (U.S. Patent No. 6,261,958) or Bowman et al. (U.S. Patent No. 6,244,941) or in view of Tench et al. (U.S. Patent No. 5,461,907). Claim 99 was rejected under 35 U.S.C. 103(a) as being unpatentable over Bowman et al. (6,244,941) alone or in view of Tench (5,461,907). Claims 100-110 were rejected under 35 U.S.C. 103(a) as being unpatentable over Crevasse et al. (6,261,958) or Bowman et al. (6,244,941) alone.

Interview Summary

Applicants Attorney, Marcus Simon, and Examiner Eileen Morgan had a phone interview on September 12, 2005 and September 14, 2005. In the phone interview, Applicants Attorney and Examiner Morgan discussed the patentability of claims 89-94 and 99-110 in comparison to the cited references. It was agreed that claims 89-94 and 99 would be cancelled. Additionally, it was agreed that if claims 100, 103-105, and 107 were amended to reflect that the plurality of conductive particles are embedded in the planarizing medium, the claims 100-110 would be patentable over the above cited references.

Claims and Rejections

As proposed to be amended claim 100 is patentable over the above cited references. The above cited references do not disclose or fairly suggest the limitations of "embedding a plurality of conductive particles in the planarizing medium." (Emphasis Added). Claims 103-105 have been amended to provide a proper antecedent basis for the acts recited therein that further limit the acts recited in independent claim 100 and not for reasons related to patentability. Claims depending from claim 100 are also patentable due to depending from a patentable base claim and further in view of the additional limitations recited in the dependent claims.

As proposed to be amended claim 107 is patentable over the above cited references. The above cited references do not disclose or fairly suggest the limitations of "[a] method for releasably attaching a planarizing medium having a plurality of embedded conductive particles to a platen of a planarization machine, comprising: positioning the planarization medium adjacent to the platen; and coupling a signal to the platen to produce an electromagnetic

attractive force between the conductive particles and the platen." (Emphasis Added). Claims depending from claim 107 are also patentable due to depending from an patentable base claim and further in view of the additional limitations recited in the dependent claims.

New dependent claims 111 and 112 have been added and also contain additional patentable subject matter.

All of the claims remaining in the application (claims 100-112) are now clearly allowable. Favorable consideration and a Notice of Allowance are earnestly solicited.

Respectfully submitted,
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Enclosures:
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